HOT AIR STATION

MODEL 3004

INSTRUCTION MANUAL

MAGNUM

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Safety Precautions.

Do not use Hot air station near any inflammable gases, paper or other dangerous materials.

Never touch the heated nozzle or allow the hot air to blow against your skin.

Before switching off,allow unit to cool down by turning the temperature to minimum for a short time.

Never obstruct air flow as this can damage the heating element.

System Includes.

3004 station

1004 Hot Air Pencil.

1,5mm & 3mm nozzles

Moulded power cord.

Cast iron spring stand

SMD removal kit.

Startup.

CAUTION: To avoid burns the following must be done when the Hot air pencil is cold.

Adjust the airflow knob for desired air flow(between 4-8 recomended)

Adjust the temperature knob for desired temperature.(380' recomended)

Select the desired tip 1,5mm or 3mm round.

Switch on the station.

Note:- When LED on the station starts flashing the air is at the set temperature.

Removing -QFP/SOP.

Pass the stainless steel wire through and under the legs of the QFP or SOP and fix to the p.c.board with adhesive tape (fig 2).

Blow hot air on the leads nearest the edge of the hand holding the wire. Carefully draw the wire outwards along the surface of the p.c.board so that it sweeps between the p.c.board and the legs of the QFP/SOP.(fig.3)

Fig.2

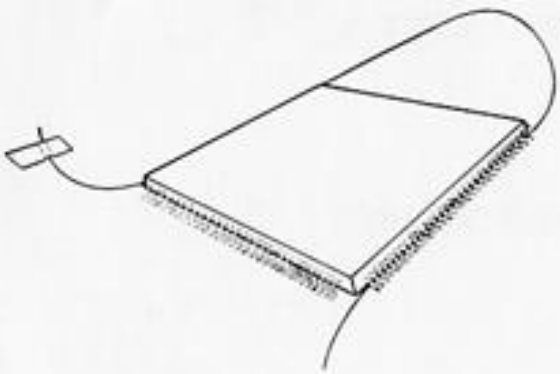
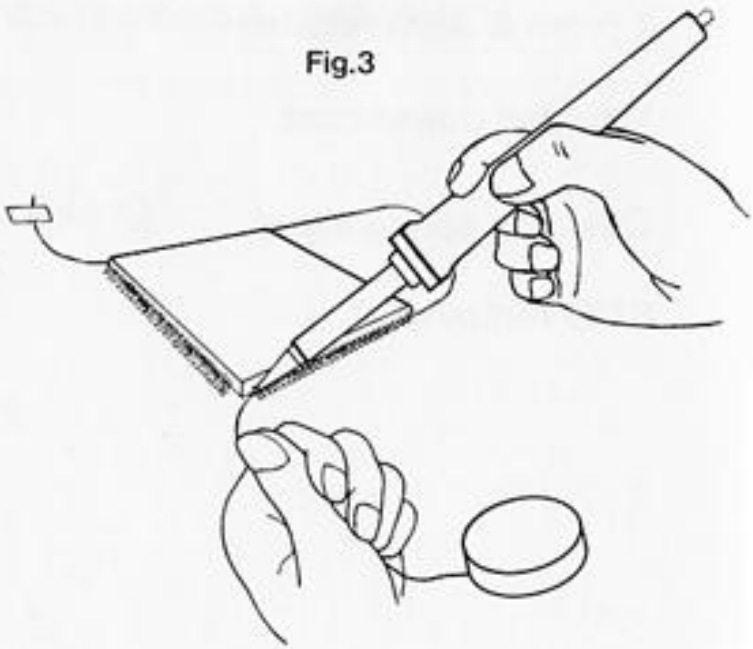


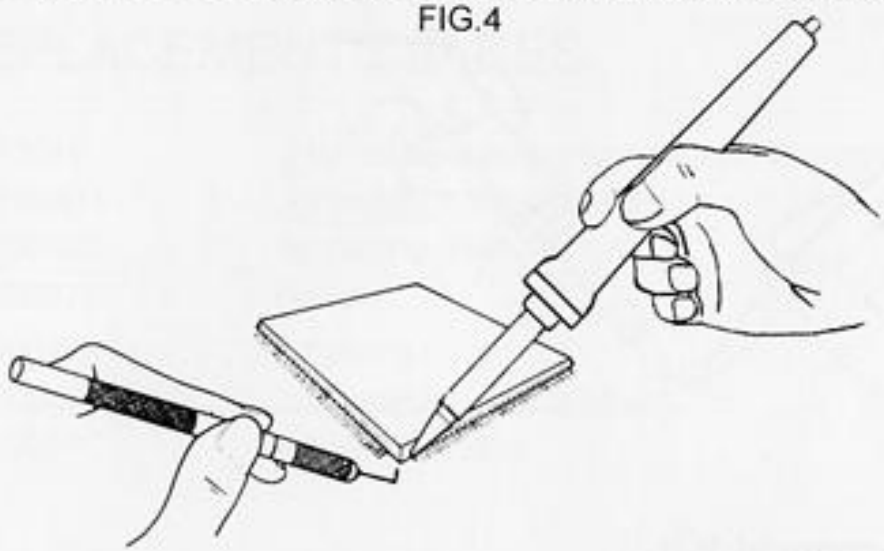
Fig.3



Removing -QFP/SOP. using wire hook.

Insert the wire hook into the holder and place under the legs of the QFP or SOP.
Blow hot air onto the legs nearest the wire.When the solder melts,carefully move the wire along under the legs. while melting the solder with the hot air pencil.(to avoid resoldering move air pencil in one direction only)fig. 4.

FIG.4



Removing PLCC using steel blade.

Insert blade,which can be cut to any shape,into holder and fasten.(fig.5)
Apply hot air continously to both the blade and legs (fig.6) Insert blade into the edge of the legs moving the hot air and blade along.
To remove a glued component after desoldering,blow hot air onto and under the component .Insert blade under component and remove.

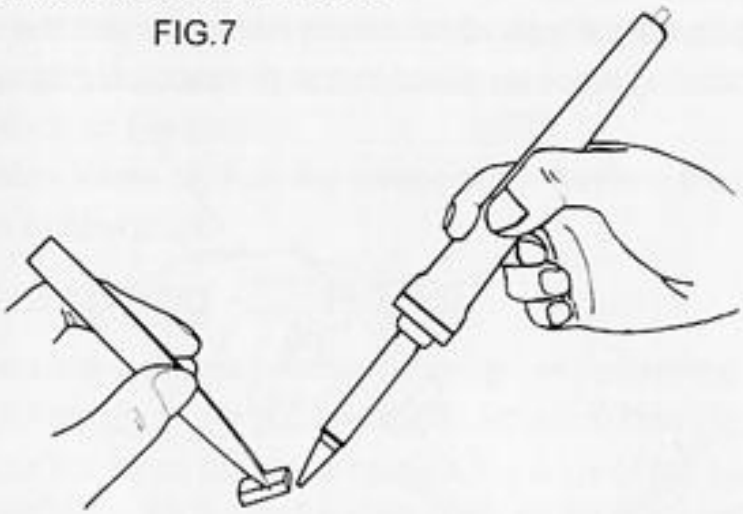
FIG.5

FIG.6

Removing chips,resistors and capacitors.

Using 3mm tip apply hot air while holding chip with tweezers.
When solder has melted,remove.(fig.7)
Steel fork can be used to lift IC's

FIG.7



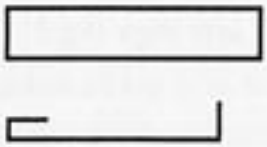
Smd Removal Kit

Air nozzle 3mm SM100402

Air nozzle 1,5 mm round SM100401

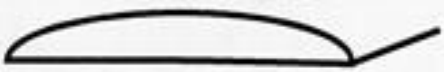
Steel blade

Wire hook.



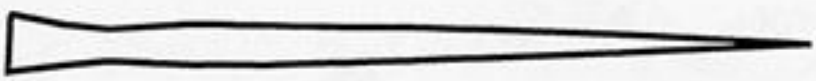
Lifting fork

Solder braid

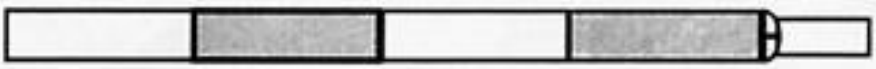


Stainless steel wire.

Tweezer



Blade holder



ACCESSORIES.

PENVAC. Vacuum pickup pencil with vacuum cups.
Special nozzles can be made.

REPLACEMENT SPARES.

SM1004E	24V 85W Heating Element with Thermocouple.
SM100401	Air nozzle 1,5mm round.
SM100402	Air nozzle 3mm
SM100272	Handle
SM300301	Air pump
SM3004PC	Temperature control board.
SM3002PC	Air control board.

SPECIFICATIONS

Power input	220v/240v 50/60Hz AC
Consumption	250W Fuse 3A
Output	24V 85W AC
Air flow	1 TO 5 Ltr/m (ADJUSTABLE)
Temperature	150'C to 450'C (ADJUSTABLE) (300'Fto 840'F)
Size	L.265mm W.225mm H.110mm
Weight	3 KG (6,6lbs)